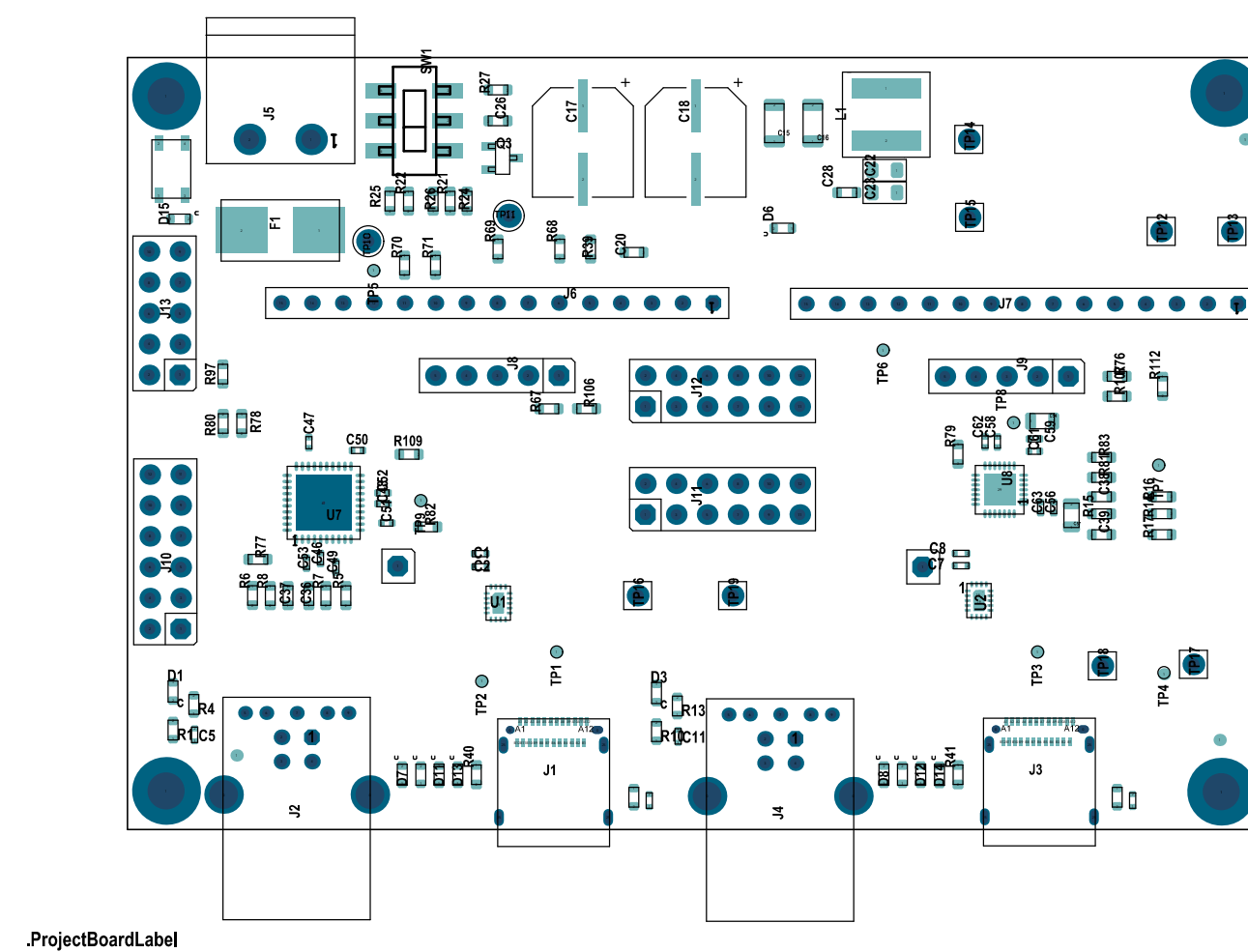


REV	ECO	Comments	Date

- ASSEMBLY NOTES:
1. WORKMANSHIP TO BE COMPLIANT WITH IPC-A-610, CLASS 2.
 2. ALL UNUSED THROUGH HOLE COMPONENT LOCATIONS SHALL BE FREE OF SOLDER.
 3. ALL COMPONENTS SHALL BE MOUNTED FLUSH TO THE BOARD, EXCEPT AS NOTED.
 4. FINISHED BOARD SHALL BE FREE OF ALL RESIDUES.
 5. THIS ASSEMBLY CONTAINS ELECTROSTATIC DISCHARGE (ESD) SENSITIVE DEVICES; STATIC-FREE HANDLING IS REQUIRED.
 6. PRODUCT WILL BE ASSEMBLED USING ROHS COMPLIANT MANUFACTURING PROCESS AND COMPONENTS.
 7. PLACE S/N LABEL INSIDE LABEL1 BOX ON BOTTOM SIDE AS INDICATED.
 8. PLACE RUBBER FEET (PAD1-PAD4) ON BOTTOM SIDE AS INDICATED.

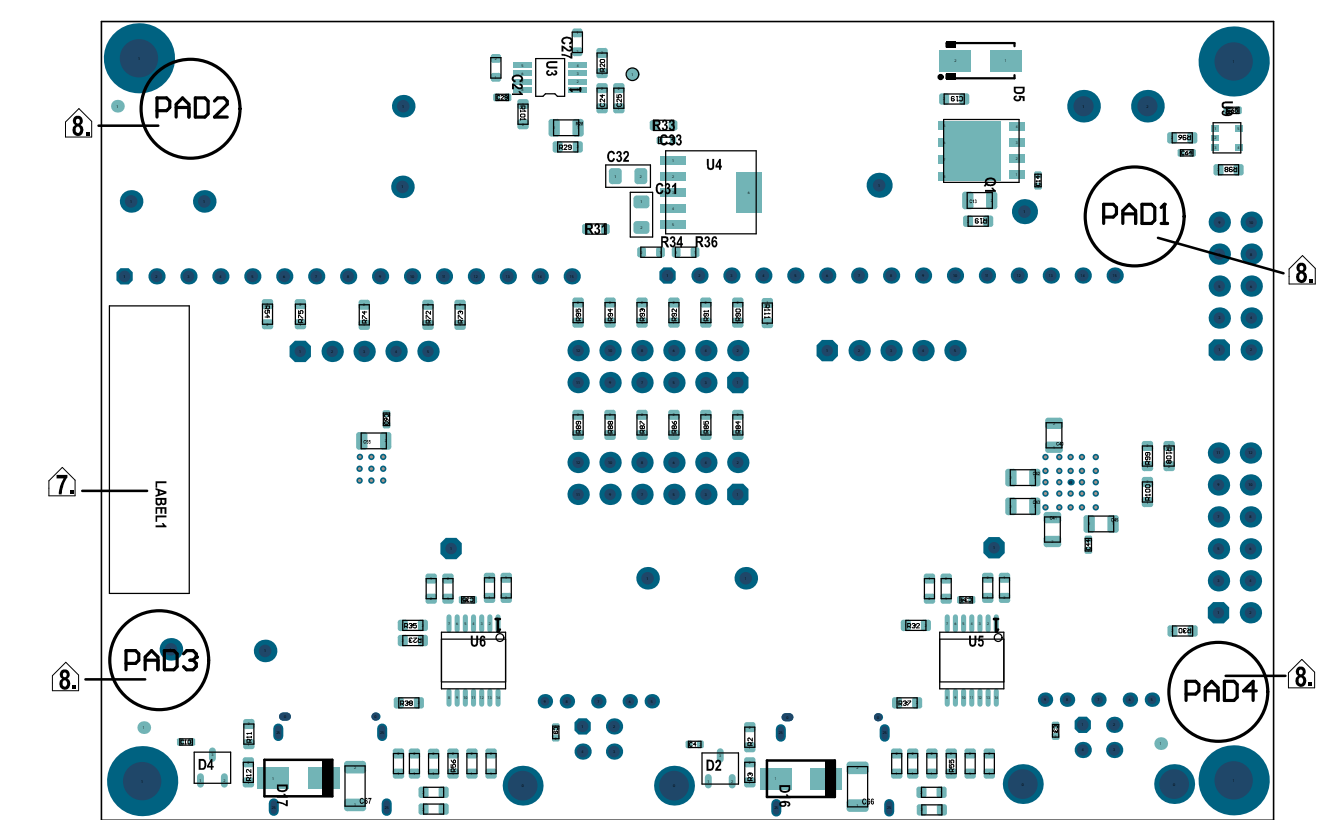


DOCUMENT NUMBER:
02-11033
M11 Assy TOP

ASSEMBLY VARIANT: No Variations

	UPD301 EVB (SRC)		PROJECT PART NUMBER: EVB-UPD301-SRC
	PCB DESIGNER: Jennifer Hancock	GERBER FILE: Top Assembly Drawing	
	ENGINEER: Mick Davis	DOCUMENT NUMBER: 02-11033 -D	DATE: 8/23/2019
	FILE NAME: UNG_8170_EVB_UPD301_SRC_C_PcbDoc	LAYER NAME: M11 Assy TOP	SCALE: 3.0

REV	ECO	Comments	Date



Bottom Assembly Drawing

 MICROCHIP <small>Microchip Technology Inc.</small> <small>32910 University Ave.</small> <small>Tulsa, OK 74134</small>	TITLE UPD301 EVB (SRC)		<small>PROJECT PART NUMBER</small>
	<small>DESIGNER</small> Jennifer Hancock	<small>DATE</small> 8/23/2019	<small>ISSUED BY</small> Jennifer Hancock
	<small>APPROVED BY</small> Mick Davis	<small>QUANTITY</small> 11033	<small>DATE</small> 8/23/2019
	<small>FILE NAME</small> UNG_B170_EVB_UPD301_SRC	<small>LAYER NAME</small> C:PcbDoc	<small>REV</small> 1

MICROCHIP
EVB-UPD301-SRC
Rev. C

